



**For Immediate Release**

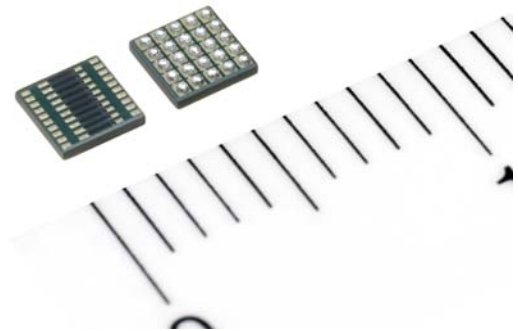
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## **TDK Develops BGA Chip Varistor with EMI Filter Function**

*One chip contains 30 elements, can be used to create 10-line arrays*

**TOKYO JAPAN, March 23, 2009** —TDK Corporation announced today that it has developed the AVF26BA12A400R201 BGA\* chip varistor (2.6 mm × 2.6 mm × 0.65 mm). The new BGA varistor has been designed with an electromagnetic interference (EMI) filter function and is ideal for applications such as mobile phones, portable music players, digital video cameras, digital still cameras, etc. Mass production is scheduled to begin in October 2009.

To provide a single chip with as much capacity as possible, each chip contains 30 elements and can be used to create 10-line ESD countermeasures. As a result, the mounting area of this product is 33% less than earlier TDK products. In addition, the added filter function controls EMI generated by devices. This makes the installation of separate EMI countermeasures components unnecessary and contributes to a further reduction of mounting area.

In recent years, mobile electronic devices have steadily become smaller while incorporating more advanced functions, and as a result, further miniaturization and integration of the electronic components used in them are necessary. In addition, the use of lower IC operating voltages is accelerating to maintain and lengthen device operating times by limiting power consumption.

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This creates environments that are even more susceptible to effects from high-voltage static electricity, and as a result, electrostatic discharge (ESD) countermeasures to prevent malfunction of devices and damage to their components are essential. TDK responded to this market need by developing the AVF series chip varistor for mounting in compact mobile devices.

For more information on this product please email [TDK\\_Varistors@tdktca.com](mailto:TDK_Varistors@tdktca.com).

*\*BGA: Abbreviation for ball grid array. Refers to an array of ball electrodes made from solder. No lead wires extend from the component, resulting in a smaller mounting area.*

### **Main Characteristics:**

Varistor electrodes	12 V
Capacitance value at 1 MHz	40 pF
Dimensions	2.6 mm × 2.6 mm × 0.65 mm

### **About TDK:**

*TDK Corporation of America (TCA) was established in 1974 in California as the sales and marketing force for electronic components in North America and Latin America. TCA has grown into a sales force of fifteen offices in the U.S. and a headquarter office located in Mount Prospect, Illinois. The combined efforts of sales, marketing and technical personnel have built the TDK name as a respected leader in the industry. Known for reliability and expertise, TDK strives to respond to all customers' needs anywhere in North America. For additional information on TDK products visit our web site at [www.tdk.com](http://www.tdk.com).*

*TDK Corporation (NYSE: TDK), a leading global electronics company based in Japan. The company was established in 1935 to commercialize "ferrite," a key material in electronics and magnetics. TDK's current product line includes ferrite materials, electronic components, factory automation solutions, anechoic chambers & test systems, magnetic heads for hard disk drives (HDD) and power supplies. Net sales in FY08 were US\$8.7 billion.*

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